

Model 150 Stratum 3, 9x14 mm OCXO

Features

- 10 to 50 MHz Frequency Range
- Compliant to Stratum 3 of GR-1244-CORE
- Surface Mount
- 3.3V or 5.0V operation
- Low Jitter/Phase Noise
- Tape and Reel Packaging

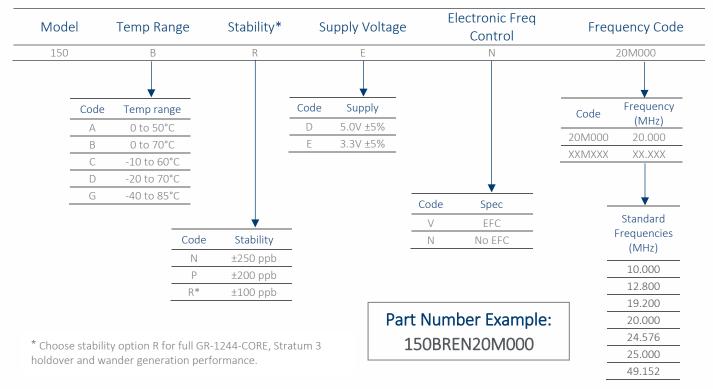
Applications

- Telecom Switching
- Wireless Communication
- Timing over Packet

Description

The CTS Model 150 is a low cost, small size, high performance OCXO. The high quality AT Quartz Crystal used in this OCXO offers high stability and low jitter/phase noise, making it the ideal choice for any telecommunications system.

Ordering Information – Table 1



Model 150 Rev. B_062016

www.ctscorp.com

Page 1 of 5

©2015 CTS® Corporation. Information/product(s) subject to change. No warranty that product(s) will meet the stated specifications for customer specific applications or test equipment. Visit www.ctscorp.com for list of applicable patent(s), more information, or to request a quote.



Part Dimensions: 9.7 × 14.9 x 7.0 mm



Electrical Specifications

Parameter	Conditions & Remarks	Min	Typical	Max	Unit
Operating Conditions					
Operating Temperature Range	T _{OP}	-40	-	85	°C
Supply Voltage	V _{CC} : 3.3V or 5.0V	3.135 4.75	3.3 5.0	3.465 5.25	Vdc
Power Consumption	Warm-up Steady State; T _A = 25°C	-	- 0.7	2.7 1	W
Load		13.5	15	16.5	рF
Frequency Stability					
Frequency	F _{NOM}	10	-	50	MHz
Initial Frequency Tolerance	@25°C, at time of shipment	-	-	±0.5	ppm
Freq. vs Temperature (See options - Table 1)	-40°C to 85°C (ref to +25C)	-	-	±100	ppb
Freq. vs Supply Voltage	V _{CC} ±5%	-	-	±50	ppb
Freq. vs Load	15 pf ±5%	-	-	±50	ppb
Freq. vs Time (Aging)	After 30 days of operation	- - -	±2 ±300 ±3	- -	ppb/day ppb/year ppm/10 yr:
Free run accuracy	All causes – 10 years	-	-	±4.6	ppm
Short Term Stability (ADEV)	1.0 sec	-	-	0.1	ppb
Warm-up time	@ 25°C, After 5 mins referenced to the freq after 1 hour on	-	-	±500	ppb
Holdover Stability (24 hours)	- Constant temperature - Over Ambient temperature (See options - Table 1)	-	-	±10 200	ppb ppb, pk-pk
Wander Generation	Meets Stratum 3 MTIE and TDEV	requirements	per Telcordia	GR-1244-COF	RE (See Table 1

CMOS Output Levels	3.3V (LVCMOS)	V _{OL}	-	-	0.4 0.4	Vde
	5.0V (HCMOS)	V _{OH}	2.4	-	-	- Vdc
			3.0	-	-	
Rise/Fall Times	10% to 90%, 15pf load		-	-	5	ns
Duty Cycle	@50% of output signal		45	50	55	%
	1 Hz 10 Hz		-	-70	-	
			-	-100	-	
Phase Noise	100 Hz		-	-125	-	dBc/Hz
(Typical for 25.0 MHz)	1 kHz		-	-142	-	UDC/ NZ
	10 kHz 100 kHz		-	-148	-	
			-	-151	-	

Model 150 Rev. B_062016

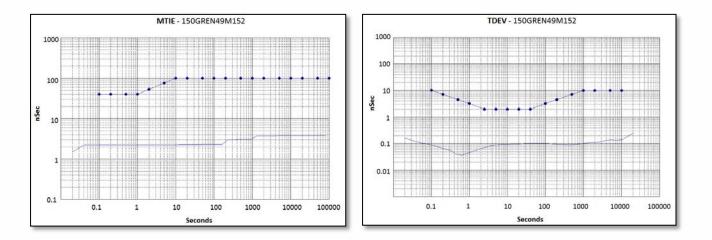
www.ctscorp.com



Electrical Specifications (Continued)

Parameter	Conditions & Remarks		Min	Typical	Max	Unit
Electronic Frequency C	Control - EFC (O	ptional)				
EFC Control Voltage	V _C	3.3V	0.0	1.65	3.3	Volts
		5.0V	0.0	2.5	5.0	VOILS
Frequency Adjust Range			±5.0	-	-	ppm
Slope	Positive, m	Positive, monotonic		-	-	
Input Impedance	Z _{IN}	Z _{IN}		-	-	Kohms
Linearity			-	-	10	%

Typical Stratum 3 Wander Generation performance per Telcordia GR-1244-CORE (locked through a 0.1Hz loop bandwidth)



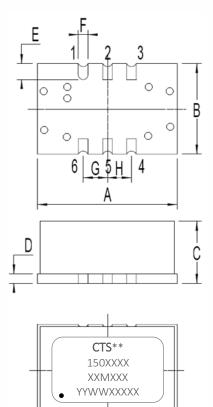


Mechanical and Environmental

Storage Temperature Range	-55°C to +105°C		
Operating Temperature Range	-40°C to +85°C		
Reflow Profile	Per IPC/JEDEC J-STD-020D; >217°C, 1.5min and 245°C (Absolute max temperature), 10 secs. Note: This product is not designed to be reflowed in an inverted position.		
Mechanical Shock	100g, 6ms, 1/2 sinewave, 3 shocks each direction along 3 mutually perpendicular planes.		
Drop	10 cm height, 3 times onto hard board with thickness of 3 cm IEC60028-2-32 test Ed.		
Bumping	40g, 6mS, 4000 ± 10 times in each of three mutually perpendicular axes		
Mechanical Vibration	Random:	Frequency range: 1Hz-4Hz-100Hz-200Hz Acceleration: 0.0001g²/Hz - 0.01g²/Hz - 0.01g²/Hz - 0.001g²/Hz Grms=1.15g. Duration: 30 minutes (per axis)	
	Sine:	10 - 55 Hz, 0.75mm DA, Sweep time 30 minutes per axis	
Thermal Shock	-40°C \sim +85°C. 0.5 hour dwells with <30 second transitions. 100 cycles		
RoHS	Lead Free, and fully compliant to RoHS Directive 2011/65/EU		
MSL	Level 2		

Mechanical Specifications

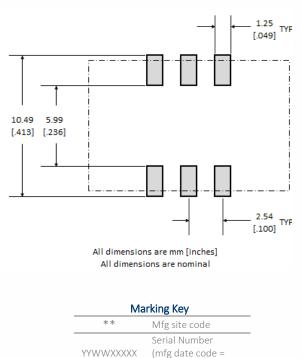
Pad termination finish: Gold flash < 10 μ inch, over Ni plated Cu



Dimension (mm) Symbol Min Max А 14.9 В 9.7 С 7.0 D 0.9 1.1 Е 1.6 1.8 F 0.9 1.1 G 2.54 nominal 2.54 nominal Н

Connection
Vc or N/C
N/C
Ground
Output
N/C
Vcc

Recommended Solder Pad Geometry



Model 150 Rev. B_062016

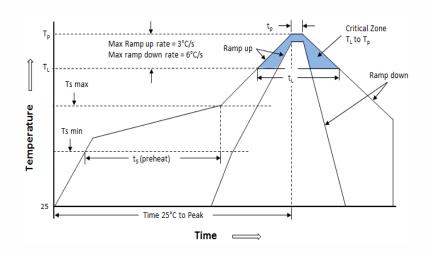
www.ctscorp.com

Page 4 of 5

first 4 digits)



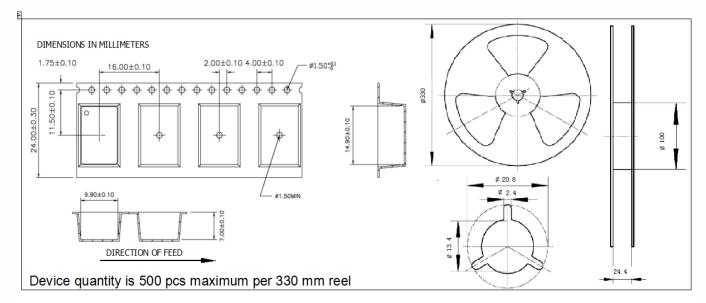
Solder Reflow



Ts max to TL(Ramp-up Rate)	3°C/s max
Preheat	
Temperature Min (Ts min)	150°C
Temperature typ (Ts)	175°C
Temperature max (Ts max)	200°C
Time (t _s)	60-120 seconds
Ramp-up Rate (T_L to T_P)	3°C/s max
Time maintained above:	
Temperature (T _L)	217°C
Time (t _L)	90 seconds max
Dook Tomporatura	245°C max for 10
Peak Temperature	seconds
Time within 5°C of peak (t_P)	20 seconds
Ramp-down Rate	6°C/s max
Time 25°C to Peak Temp (t)	8 minutes max
lete. Tomporaturas represent d	aviaa hadu tamparatur

Note: Temperatures represent device body temperature.

Packing: Tape and Reel



Model 150 Rev. B_062016

www.ctscorp.com

Page 5 of 5